
**MEMS motion sensor: L20G20IS ultra-compact two-axis gyroscope
for optical image stabilization**

Introduction

The L20G20IS is a two-axis MEMS gyroscope for image stabilization applications. It includes a sensing element and an IC interface capable of providing the measured angular rate to the application through an SPI digital interface.

The unique sensing element is manufactured using a dedicated micromachining process developed by STMicroelectronics to produce inertial sensors and actuators on silicon wafers.

The IC interface is manufactured using a CMOS process that allows a high level of integration to design a dedicated circuit which is trimmed to better match the characteristics of the sensing element.

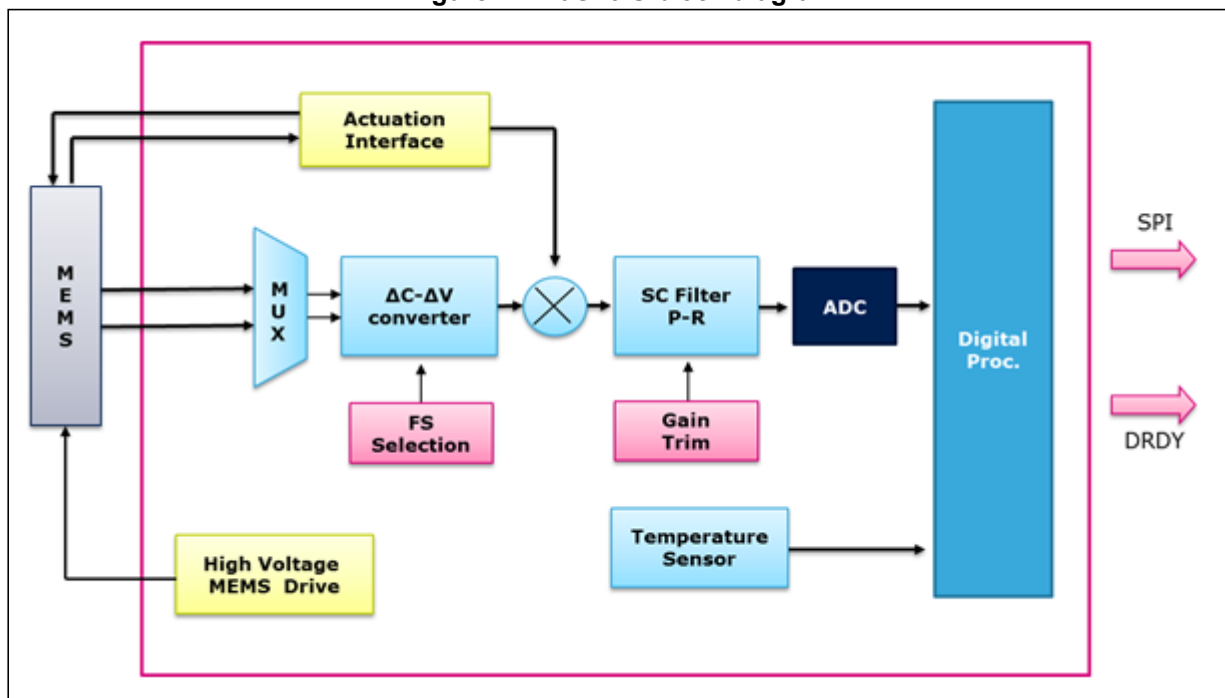
The L20G20IS is available in a plastic land grid array (LGA) package and can operate over a temperature range of -40 °C to +85 °C.

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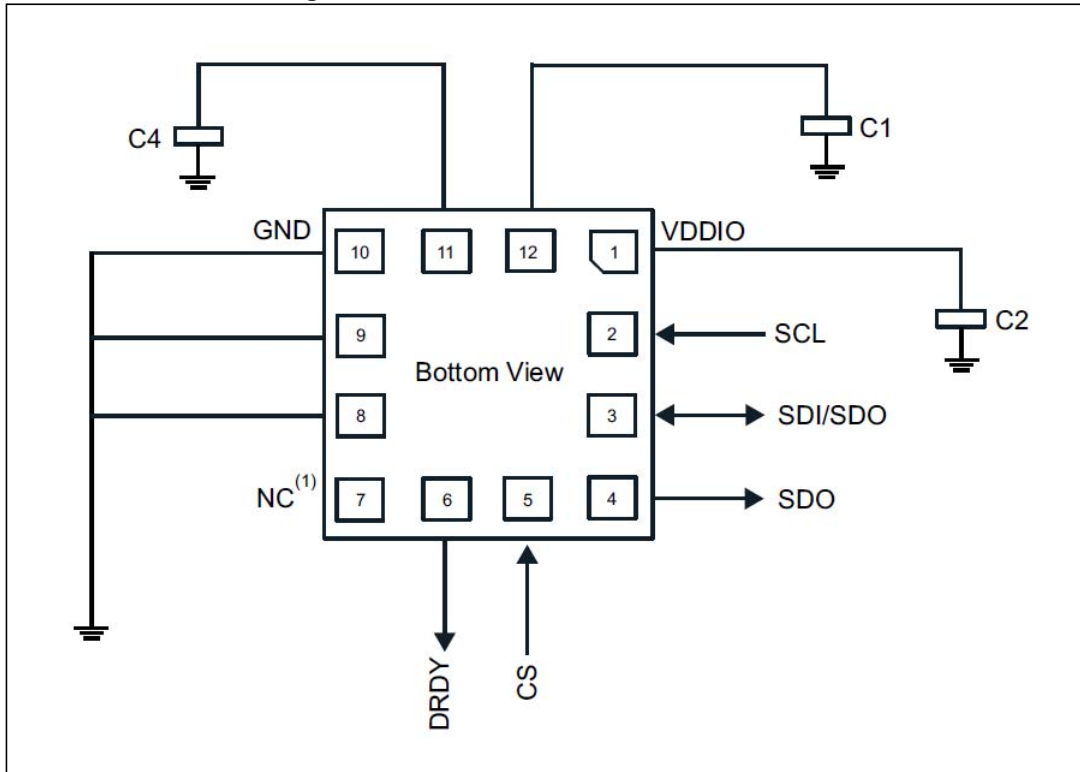
1 Readout chain

Figure 1. L20G20IS block diagram



2 Electrical connections and values for external components

Figure 2. L20G20IS electrical connections



1. Leave pin electrically unconnected and soldered to PCB.

Table 1. External components

| External component | Value | Purpose |
|--------------------|--------------------|--------------------|
| C1 | 100 nF | Decoupling |
| C2 | 100 nF | Decoupling |
| C4 | 100 nF (5 V class) | Internal regulator |

Note: Power supply decoupling capacitors (C1, C2) should be placed as near as possible to the supply pins on the device (common design practice).

2.1 Internal pin status

Table 2. Internal pin status

| Pin # | Pin name | Function | Status |
|-------|----------|--|--------------------------------|
| 1 | VDDIO | Power supply for I/O pins | |
| 2 | SCL | Clock line for SPI interface | Default: input without pull-up |
| 3 | SDI/SDO | Serial data input (SDI) 3-wire interface serial data output (SDO) | Default: input without pull-up |
| 4 | SDO | Serial data output (SDO) | Default: input without pull-up |
| 5 | CS | Chip-select line | Default: input without pull-up |
| 6 | DRDY | Data ready signal | Default: push-pull to gnd |
| 7 | RES | Leave unconnected | Default: push-pull to gnd |
| 8 | RES | Connect to GND | Internally unconnected |
| 9 | RES | Connect to GND | Internally unconnected |
| 10 | GND | 0 V power supply | |
| 11 | REG | Capacitance connection pin for internal regulator | |
| 12 | VDD | Power supply | |

3 Registers

Table 3. Register address map

| Register name | Address | Bit7 | Bit6 | Bit5 | Bit4 | Bit3 | Bit2 | Bit1 | Bit0 |
|-----------------|---------|----------|-----------|---------|---------|----------|-------------------|------------|-----------|
| WHO_AM_I | 00h | 1 | 1 | 0 | 1 | 1 | 0 | 1 | 0 |
| TEMP_OUT_L | 01h | Temp3 | Temp2 | Temp1 | Temp0 | 0 | 0 | 0 | 0 |
| TEMP_OUT_H | 02h | Temp11 | Temp10 | Temp9 | Temp8 | Temp7 | Temp6 | Temp5 | Temp4 |
| OUT_X_L | 03h | XD_7 | XD_6 | XD_5 | XD_4 | XD_3 | XD_2 | XD_1 | XD_0 |
| OUT_X_H | 04h | XD_15 | XD_14 | XD_13 | XD_12 | XD_11 | XD_10 | XD_9 | XD_8 |
| OUT_Y_L | 05h | YD_7 | YD_6 | YD_5 | YD_4 | YD_3 | YD_2 | YD_1 | YD_0 |
| OUT_Y_H | 06h | YD_15 | YD_14 | YD_13 | YD_12 | YD_11 | YD_10 | YD_9 | YD_8 |
| DATA_STATUS_OIS | 0Ah | XYOR_OIS | XOR_OIS | YOR_OIS | 0 | XYDA_OIS | XDA_OIS | YDA_OIS | 0 |
| CTRL1_OIS | 0Bh | BOOT | DR_PULSED | BLE | SIM | ODU | ORIENT | PW1 | PW0 |
| CTRL2_OIS | 0Ch | SignX | SignY | LPF_BW1 | LPF_BW0 | 0 | HP_RST | SW_RST | HPF |
| CTRL3_OIS | 0Dh | 0 | 0 | 0 | ST_SIGN | ST_EN | 0 | H_L_ACTIVE | LP_BW2 |
| CTRL4_OIS | 0Eh | 0 | 0 | 0 | DRDY_EN | 0 | TEMP_DATA_ON_DRDY | DRDY_OD | 0 |
| OFF_X | 0Fh | 0 | OFFX6 | OFFX5 | OFFX4 | OFFX3 | OFFX2 | OFFX1 | OFFX0 |
| OFF_Y | 10h | 0 | OFFY6 | OFFY5 | OFFY4 | OFFY3 | OFFY2 | OFFY1 | OFFY0 |
| OIS_CFG_REG | 1Fh | 0 | 0 | 0 | 0 | FS_SEL | 0 | HPF_BW[1] | HPF_BW[0] |

4 Operating modes

The L20G20IS features three operating modes, normal mode, sleep mode and power-down, which are described in the following paragraphs.

To select the operating mode, the PW[1:0] bits in CTRL1_OIS (0Bh) are used.

Table 4. Operating selection

| PW1 | PW0 | Operating mode selection |
|-----|-----|--------------------------|
| 0 | 0 | Power-down |
| 0 | 1 | Power-down |
| 1 | 0 | Sleep mode |
| 1 | 1 | Normal mode |

4.1 Power-down mode

When the device is in power-down mode, almost all internal blocks of the device are switched off to minimize power consumption. The SPI interface is still active to allow communication with the device. The content of the configuration registers is preserved and output data registers are not updated, therefore keeping the last data sampled in memory before going into power-down mode.

4.2 Sleep mode

When the device is set in sleep mode, the reading chain is completely turned off, while the mass is kept in oscillation, resulting in a lower power consumption than in normal mode. In this condition the device turn-on time is significantly reduced, allowing simple external power cycling.

4.3 Normal mode

When in normal mode, the angular rate data are generated at 9.33 kHz data rate (ODR); the full scale can be selected through the bit FS_SEL in OIS_CFG_REG (1Fh). Temperature data are generated at 70 Hz.

Table 5. Full-scale selection

| FS_SEL | Full-scale selected |
|--------|---------------------|
| 0 | ±100 dps |
| 1 | ±200 dps |

5 Startup sequence

Once the device is powered up, it automatically downloads the calibration coefficients from the embedded Flash to the internal registers. When the boot procedure is completed, i.e. after approximately 10 milliseconds, the device automatically enters power-down mode. To turn on the device and gather angular rate data, the device must be set in normal mode using the PW[1:0] bits in CTRL1_OIS (0Bh).

The following general-purpose sequence can be used to configure the device:

1. Write OIS_CFG_REG -- FS selection and HPF configuration (only if HPF is used)
2. Write CTRL2_OIS and CTRL3_OIS -- Digital LPF configuration and HPF enable (only if HPF is used)
3. Write OFF_X and OFF_Y -- User offset correction (not mandatory)
4. Write CTRL1_OIS -- Set the gyro in normal mode
5. Write CTRL2_OIS -- HPF enable reset (only if HPF is used)

The calibration steps for the OFF_X (0Fh) and OFF_Y (10h) registers are respectively -0.98 dps/LSB and 0.98 dps/LSB.

After power-up, the calibration coefficients can be re-loaded by setting the BOOT bit in the CTRL1_OIS (0Bh) register to 1. The boot request is executed as soon as the internal oscillator is turned on. It is possible to set this bit while in power-down mode: in this case, it will be served at the next normal or sleep mode selected. The procedure requires 10 milliseconds. During the boot time the registers are not accessible.

If a reset to the default value of the control registers is required, it can be performed by setting the SW_RST bit in the CTRL2_OIS (0Ch) register to 1. The procedure requires 1 millisecond.

5.1 Understanding angular rate data

The measured angular rates are sent to the OUT_X_H (04h), OUT_X_L (03h), OUT_Y_H (06h) and OUT_Y_L (05h) registers. These registers contain, respectively, the most significant part and the least significant part of the angular rate signals acting on the X and Y axes.

The complete angular rate data for the X and Y channels are given by the concatenation OUT_X_H & OUT_X_L (OUT_Y_H & OUT_Y_L) and are expressed as a 2's complement number.

Angular rate data are represented as 16-bit numbers.

5.2 Reading angular rate data

5.2.1 Using the status register

The device is provided with a status register, DATA_STATUS_OIS (0Ah), which should be polled to check when a new set of data is available. The procedure is as follows:

1. Read DATA_STATUS_OIS
2. If DATA_STATUS_OIS(3) = 0, then go to 1
3. If DATA_STATUS_OIS(7) = 1, then some data have been overwritten
4. Read OUTX_L
5. Read OUTX_H
6. Read OUTY_L
7. Read OUTY_H
8. Go to 1

The check performed at step 3 allows understanding whether the reading rate is adequate compared to the data production rate. If one or more angular rate samples have been overwritten by new data, because of a reading rate that is too slow, the XYOR_OIS bit of DATA_STATUS_OIS (0Ah) is set to 1.

The overrun bits are automatically cleared when all the data present inside the device have been read and new data have not been produced in the meantime.

5.2.2 Using the data-ready (DRDY) signal

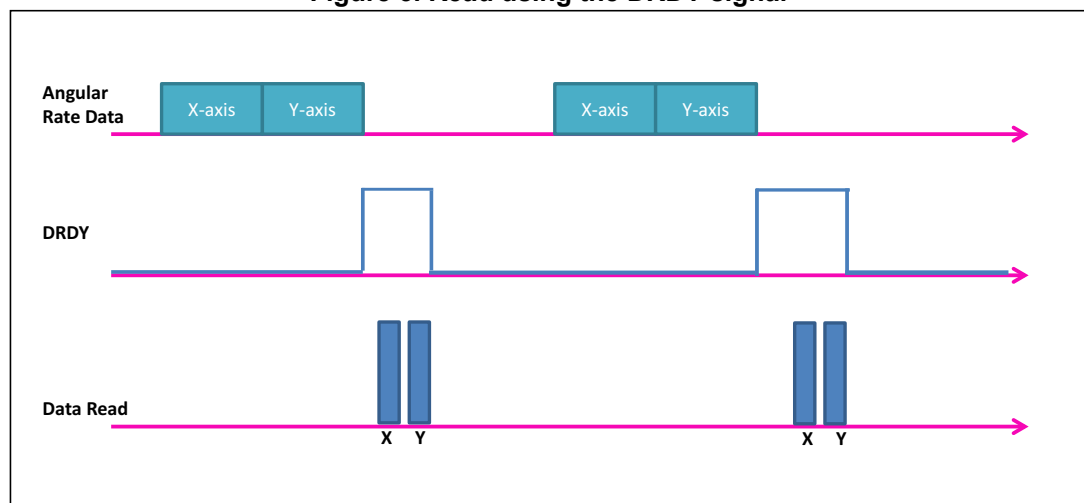
The device may be configured to have one HW signal to determine when a new set of measurement data is available to be read. This signal is equivalent to the XYDA_OIS bit in DATA_STATUS_OIS (0Ah). The DRDY_EN bit in CTRL4_OIS (0Eh) has to be set to '1' to enable the data-ready interrupt on the DRDY pin.

To properly perform a synchronous read, the angular rate data have to be read every time the DRDY pin goes high.

The DRDY signal can be latched (default condition) or pulsed if the DR_PULSED bit in CTRL1_OIS (0Bh) is set to '1'. The DRDY pin is set by default as a push-pull output, but it can be configured as an open-drain output by setting the DRDY_OD bit in CTRL4_OIS (0Eh) to '1'. The DRDY signal is configured as active high by default. It can be configured as active low by setting the H_L_ACTIVE bit in the CTRL3_OIS (0Dh) register to 1.

The interrupt is then reset when the output of all the channels has been read (OUT_X_L (03h), OUT_X_H (04h), OUT_Y_L (05h), and OUT_Y_H (06h)).

Figure 3. Read using the DRDY signal



5.3 Output data update (ODU)

By default the output data update (ODU) function is enabled in the L20G20IS, preventing the update of the output registers until MSB and LSB have been read.

This feature avoids reading values (most significant and least significant parts of the angular rate data) related to different samples. In particular, when the ODU bit is deasserted, the data registers related to each channel always contain the most recent angular rate data produced by the device, but, if a read of a given pair (i.e. OUT_X_H and OUT_X_L, OUT_Y_H and OUT_Y_L) is initiated, the refresh for that pair is blocked until both MSB and LSB parts of the data are read.

The ODU only guarantees that OUT_X(Y)_L and OUT_X(Y)_H have been sampled at the same moment. For example, if the reading speed is too slow, it may be possible to read the angular rate data of the x-axis sampled at T1 while the y-axis data sampled at T2.

The ODU function can be configured in CTRL1_OIS (0Bh). If the ODU bit is asserted, the output registers are updated continuously.

5.4 Big-little endian selection

In the L20G20IS it is possible to swap the content of the lower and the upper part of the angular rate registers (i.e. OUT_X_H with OUT_X_L), to be compliant with both little-endian and big-endian data representations.

"Little Endian" means that the low-order byte of the number is stored in memory at the lowest address, and the high-order byte at the highest address. (The little end comes first).

This mode corresponds to bit BLE in CTRL1_OIS (0Bh) set to 0 (default configuration).

On the contrary, "Big Endian" means that the high-order byte of the number is stored in memory at the lowest address, and the low-order byte at the highest address.

The following table provides a few basic examples of the gyroscope data that is read in the data registers when the device is subjected to a given angular rate.

Table 6. Output data registers content vs. angular rate (FS = 100 dps)

| Angular rates values | BLE = 0 | | BLE = 1 | |
|----------------------|------------------|---------------|---------------|---------------|
| | Register address | | | |
| | OUT_X_H (04h) | OUT_X_L (03h) | OUT_X_H (04h) | OUT_X_L (03h) |
| 0 dps | 00h | 00h | 00h | 00h |
| 43 dps | 2Ch | A4h | A4h | 2Ch |
| 87 dps | 59h | 49h | 49h | 59h |
| -43 dps | D3h | 5Ch | 5Ch | D3h |
| -87 dps | A6h | B7h | B7h | A6h |

5.5 Orientation configuration

On the L20G20IS it is possible to change the sign and the orientation of the gyroscope axes through the SignX and SignY bits of the register CTRL2_OIS (0Ch) and the ORIENT bit of the CTRL1_OIS (0Bh) register. In particular the SignX and SignY bits can be used to invert the sign of the X and Y-axis respectively.

The ORIENT bit in the CTRL1_OIS (0Bh) register allows changing the orientation of the X and Y axes as given in the table below.

Table 7. Orientation configuration

| ORIENT | OUT_X_L, OUT_X_H | OUT_Y_L, OUT_Y_H |
|--------|------------------|------------------|
| 0 | X-axis | Y-axis |
| 1 | Y-axis | X-axis |

6 Temperature sensor

The L20G20IS automatically measures the temperature and provides the data through the TEMP_OUT_L (01h) and TEMP_OUT_H (02h) registers, at a data rate of 70 Hz.

For the temperature sensor, the data-ready signal can be driven to the DRDY pad by setting the TEMP_DATA_ON_DRDY bit in the CTRL4_OIS (0Eh) register to 1.

The complete temperature data are given by the concatenation of TEMP_OUT_L (01h) and TEMP_OUT_H (02h), as two's complement data in 12-bit format, left-justified, with a sensitivity of 0.0625 °C/digit. The output of the temperature sensor is 0 at 25 °C.

The L20G20IS allows swapping, by setting the BLE bit of the CTRL1_OIS (0Bh) register, the content of the lower and the upper part of the temperature output data registers.

The following table provides a few basic examples of the temperature data that is read in the data registers when the device is subject to a given temperature.

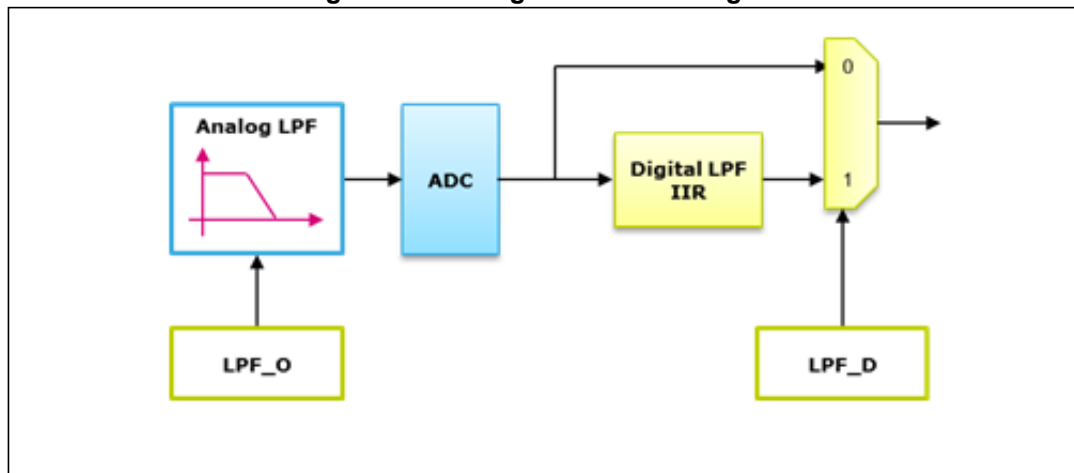
Table 8. Output data registers content vs. temperature

| Temperature values | BLE = 0 | | BLE = 1 | |
|--------------------|------------------|------------------|------------------|------------------|
| | Register address | | | |
| | TEMP_OUT_H (02h) | TEMP_OUT_L (01h) | TEMP_OUT_H (02h) | TEMP_OUT_L (01h) |
| 0 °C | E7h | 00h | 00h | E7 |
| 25 °C | 00h | 00h | 00h | 00h |
| 50 °C | 19h | 00h | 00h | 19h |

7 Filtering chain

The filtering chain for the L20G20IS appears in the figure below.

Figure 4. Filtering chain block diagram



7.1 High-pass filtering chain

The L20G20IS integrates a 1st order digital high-pass filter and it can be enabled by setting the HPF bit in CTRL2_OIS (0Ch) to '1'.

Using the HPF_BW[1:0] bits in OIS_CFG_REG (1Fh), it is possible to select the high-pass filter cutoff frequency as indicated in [Table 9](#).

If the HPF bit is set to '0', then the content of the HPF_BW[1:0] bits is not considered.

Figure 5. HPF chain block diagram

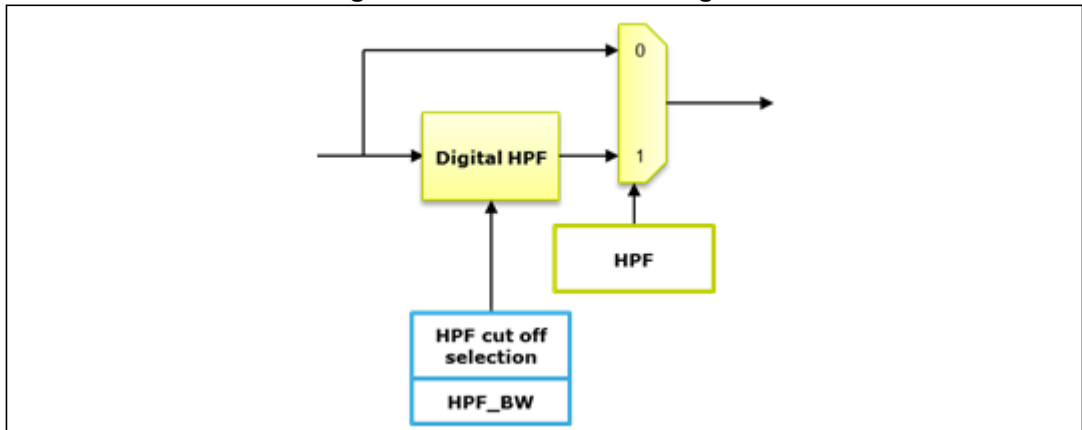
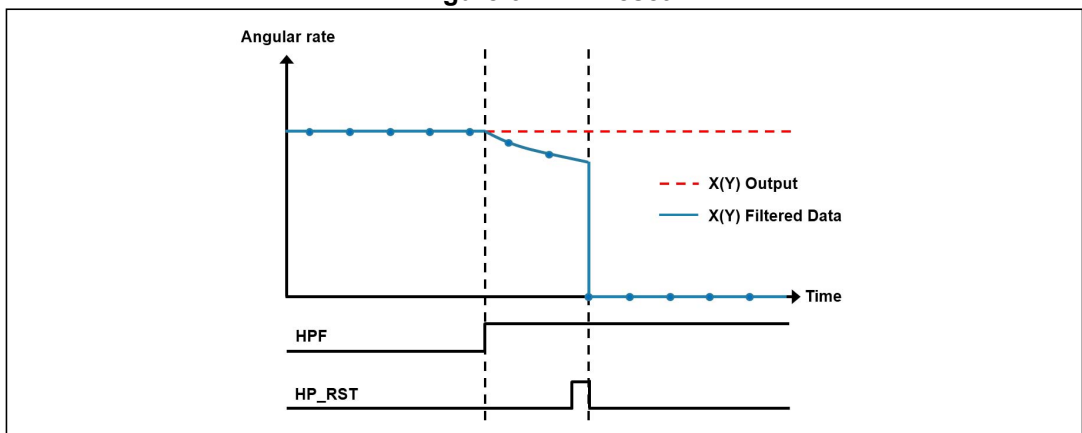


Table 9. High-pass filter cutoff frequency selection

| HPF_BW[1] | HPF_BW[0] | HPF cutoff [Hz] |
|-----------|-----------|-----------------|
| 0 | 0 | 0.023 |
| 0 | 1 | 0.091 |
| 1 | 0 | 0.324 |
| 1 | 1 | 1.457 |

The high-pass filter can be reset instantly by deleting the DC component of the angular rate. This reset can be performed by setting the HP_RST bit in the CTRL2_OIS (0Ch) register to '1'. HP_RST automatically resets to 0.

Figure 6. HPF reset



7.2 Low-pass filtering chain

The L20G20IS integrates a programmable digital low-pass filter.

It can be configured through the LP_BW1 and LP_BW0 bits of the register CTRL2_OIS (0Ch) and the LP_BW2 bit of the register CTRL3_OIS (0Dh).

The following table shows the digital LPF bandwidth, based on the LP_BW2, LP_BW1 and LP_BW0 bits settings.

Table 10. Low-pass filter bandwidth selection

| LPF_BW2 | LP_BW1 | LP_BW0 | LPF Bandwidth [Hz] | Phase delay [°] |
|---------|--------|--------|--------------------|-----------------|
| 0 | 0 | 0 | 290 | 7 @ 20 Hz |
| 0 | 0 | 1 | 210 | 9 @ 20 Hz |
| 0 | 1 | 0 | 160 | 11 @ 20 Hz |
| 0 | 1 | 1 | 450 | 5 @ 20 Hz |
| 1 | x | x | 1150 | 1 @ 10 Hz |

8 Self-test

The embedded self-test functions allows checking the device functionality without moving it.

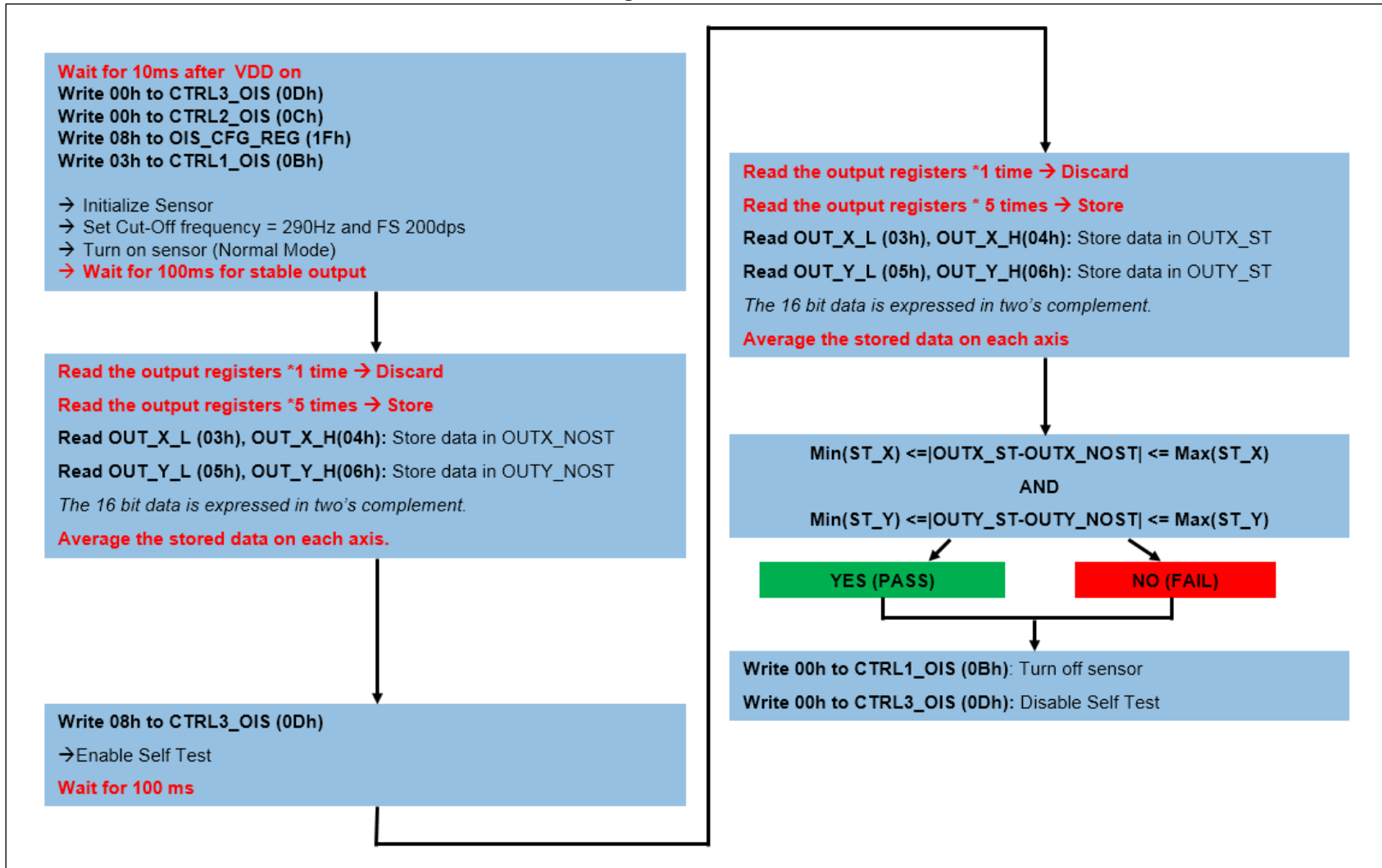
It allows testing the mechanical and electrical parts of the gyroscope sensor. When the self-test is activated, an actuation force is applied to the sensor, simulating a definite Coriolis force, and the seismic mass is moved by means of this electrostatic test-force. In this case the sensor output exhibits an output change.

The self-test function can be enabled through the ST_EN bit of the CTRL3_OIS (0Dh) register. The self-test sign can be selected through the ST_SIGN bit of the CTRL3_OIS (0Dh) register: if it is enabled, the self-test sign is inverted.

When the gyroscope self-test is active, the sensor output level is given by the algebraic sum of the signals produced by the velocity acting on the sensor and by the electrostatic test force.

The complete gyroscope self-test procedure is indicated in the following figure.

Figure 7. Self-test



9 Revision history

Table 11. Document revision history

| Date | Revision | Changes |
|-------------|----------|-----------------|
| 23-Feb-2018 | 1 | Initial release |

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